MSKSEMI















ESD

TVS

TSS

MOV

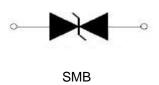
GDT

PLED

Brodnet data speet

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Features

Low capatcitance
Cannot be damaged by voltage
Will not fatigue
Eliminate voltage overshoot
Glass passivated junction
Halogen free and RoHS compliant

Mechanical Data

CASE: SMB(DO-214AA) Molded Plastic UL Flammability Classification Rating 94V0 Mounting Position:Any

Maximum Ratings & Thermal Characteristics

(Ratings at 25°C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Units	Remarks
Peak Pulse Voltage	V _{PP}	6000	V	10/700us
Peak Pulse Current	lpp	100	А	10/1000u s
Peak Pulse Current	I _{PK}	400	Α	8/20us
Peak One-cycle Surge Current	I _{TSM}	30	А	60Hz
Rate of Rise of Current	di/dt	500	A/us	
Typical Thermal Resistance Junction to Lead	R _{θJL}	20	°C/W	
Typical Thermal Resistance Junction to Ambient	$R_{ heta JA}$	100	°C/W	
Operating Temperature Range	TJ	-40 to 150	°C	
Storage Temperature Range	T _{STG}	-55 to 150	°C	

Electrical Characteristics

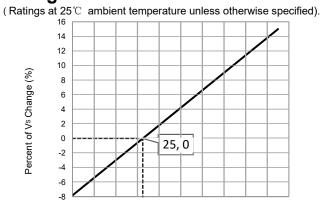
(Ratings at 25 °C ambient temperature unless otherwise specified).

Part Number	Marking	V s @100KV/S V MAX	I _{S_LMT} mA	V _T @ I _T ∨ MAX	I _T	I _D @ V□ uA MAX	V _D	C _O @1MHz,2V _{DC} pF TYP	I н mA MIN
P0080SC-MS	E-8C XXXX	25	500	4	2.2	5	6	105	40
P0220SC-MS	P02C XXXX	30	500	4	2.2	5	15	105	40
P0300SC-MS	P03C XXXX	40	500	4	2.2	5	25	100	40
P0640SC-MS	P06C XXXX	77	800	4	2.2	5	58	95	120
P0720SC-MS	P07C XXXX	88	800	4	2.2	5	65	95	120
P0900SC-MS	P09C XXXX	98	800	4	2.2	5	75	95	120
P1100SC-MS	P11C XXXX	130	800	4	2.2	5	90	90	120
P1300SC-MS	P13C XXXX	160	800	4	2.2	5	120	90	120
P1500SC-MS	P15C XXXX	180	800	4	2.2	5	140	85	120
P1800SC-MS	P18C XXXX	220	800	4	2.2	5	170	80	120
P2300SC-MS	P23B XXXX	260	800	4	2.2	5	190	75	120
P2600SC-MS	P26C XXXX	300	800	4	2.2	5	220	70	120
P3100SC-MS	P31C XXXX	350	800	4	2.2	5	275	65	120
P3500SC-MS	P35C XXXX	400	800	4	2.2	5	320	60	120
P4500SC-MS	P45C XXXX	550	800	4	2.2	5	400	45	120



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Ratings and Characteristic Curves



 T_J - Junction Temperature (°C) Fig.1 - Peak Pulse Current Rating

20 40 60 80 100 120 140 160

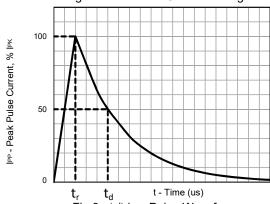


Fig.3 - tr/td us Pulse Waveform 10000 1000 IPP - Peak Pulse Current (A) 100 10 1 0.1 1000 td - Pulse Width (us)

Fig.5 - Peak Pulse Current Rating

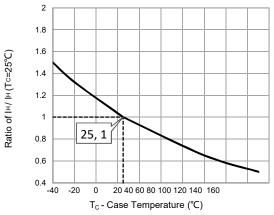
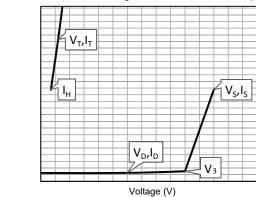
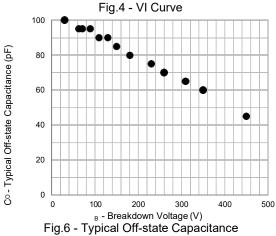


Fig.2 - Normalized DC Holding Current vs. Case Temperature

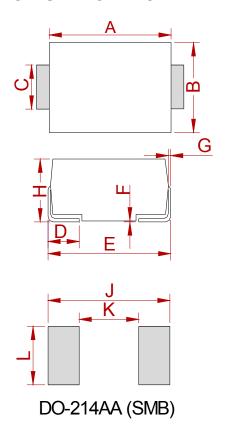


Current (A)





PACKAGE MECHANICAL DATA



	Dimensions					
Ref.	Millir	neters	Inches			
	Min.	Max.	Min.	Max.		
Α	4.25	4.75	0.167	0.187		
В	3.30	3.94	0.130	0.155		
С	1.85	2.21	0.073	0.087		
D	0.76	1.52	0.030	0.060		
Е	5.08	5.59	0.200	0.220		
F	0.051	0.203	0.002	0.008		
G	0.15	0.31	0.006	0.012		
Н	2.11	2.44	0.083	0.096		
J	6.80		0.270			
K		2.60		0.100		
L	2.40		0.090			

REEL SPECIFICATION

P/N	PKG	QTY
PxxxxSC-MS	SMB	3000



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